



## Next Generation Kinetis K Series – K2, and L Series MCUs FTF-IND-F0472

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External Use

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### Agenda

- Kinetis Microcontroller Solutions Introduction
- General Purpose Kinetis K Product Lines
  - Kinetis K-Series
  - Kinetis K2
- General Purpose Kinetis L Product Lines
- Additional Resources
  - Enablement

External Use

- Kinetis Minis support (CSP)



## K2 the Next Generation of Kinetis K Solutions

Leadership in Cortex-M World's Broadest, Most Scalable Portfolio... ...with Best-in-Class Tools and Software support!









### Kinetis Microcontroller Solutions Introduction





### **ARM SOC Portfolio's**

#### How to Choose an ARM® Core & Supplier



#### Who is the Most Comprehensive ARM<sup>®</sup> Supplier?\*\*



### **Unbound Scalability from lowest-power to higher performances**

1

Higher Performances up to 180MHz

with FPU – 50% faster than previous generation with double of RAM memory

2

Product breadth ARM® Cortex®-M0+ to M4 with 900+ code compatible product offerings, 60+ pin for pin compatible

devices that span multiple families

3

#### Lowest power to highest

External Use 5

functionality Energy efficient battery powered products to analog intensive sensing products.





Kinetis MCU's

900+ Products

Kinetis L Series 200 products (M0+)









### **Kinetis General Purpose Product Lines**

		Kinetis L Series	Kinetis E Series	Kinetis K Series				
	Processor	ARM® Cortex™-M0+	ARM® Cortex™-M0+	ARM® Cortex™-M4 ( with optional SPFPU )				
Performance		Up to 48MHz	Up to 48MHz	Up to 50 / 72 / 100 / 120 / 150 / 180MHz				
	Ultra Low Power	Typical ~50uA/MHz (VLPR Mode)	na	Typical ~130uA/MHz (VLPR Mode)				
	Memory	8kB – 256kB Flash 1kB – 32kB SRAM	8kB – 128kB Flash 1kB – 16kB SRAM	32kB – 2MB Flash 8kB – 256kB SRAM				
	Pin-Count	16 – 121 Pin	16 – 80 Pin	32 – 256 Pin	Freescale free			
	Features	Pacalina / Mixed Signal	5V / EMC / Safety (CRC)	Baseline / Mixed-Signal and optional	RTOS called MQX www.freescale.com/MQX including USB /			
MQX-Lite +USB and Peripherals Drivers (also within Processor Expert – Code Generator)		and optional Segment LCD, USB	Control (Flextimer) and optional Segment LCD, CAN	FlexMemory, USB, Segment LCD, CAN, Ethernet, Graphic LCD, DRAM-CTRL, NAND-Flash- CTRL, Crypto, Anti-Tamper	Ethernet / MS File System / Peripherals Driver			
	Price	<b>From \$0.49</b> ( MKL02x, 8KB, 16QFN )	From \$0.78 ( MKE02x, 16KB, 32LQFP )	<b>From \$0.79</b> ( MK02, 64KB, 32QFN )	-			
	Demo Board	www.freescale.com/FREEDOM www.freescale.com/TOWER						
		w	Note: Availability device dependent					

### **Kinetis K Series MCU Portfolio**

#### **First Generation Key Differentiators**

K70 Family

#### **Next Generation Key Differentiators**

**Graphic Controller** 

#### **Power / Processing Efficiency**

- Excel in Power Efficiency
- Cortex-M4 w/ FPU >100MHz from 64KB to 2MB of Flash
- Power conscious peripherals

#### **Streamline Feature Set**

- Smart Integration: right features at the right price.
- Save BOM cost with Crystal-less USB device functionality

#### Introduction of New Tools

- Kinetis Software Development Library (SDK)
- -Kinetis Development Studio
- Embed support
- expansion of low-cost Freescale
- Freedom development platform

#### Feature Rich MCUs

#### Analog Mixed Signal

- Up to 4x 16-bit ADCs
- -16-bit ADCs w/ PGAs
- AmpOp
- -TriAmp

#### FlexMemory

- EEPROM
- Read-While-Write

#### HMI:

- -Touch Sensing
- Segment LCD
- Graphic LCD

+ Graphics LCD	
Ethernet	
K60/K61 Family Ethernet, USB	K64F Family Ethernet + USB + High RAM
K5x Family (Measurement) Analog, USB, SLCD, Ethernet, Encryption	Measurement
K40 Family Segment LCD + USB	Segment I CD
K30 Family Segment LCD	Segment Leb
USB	K24F Family USB + High RAM
K20 Family USB	K21/K22 Family USB w/ opt. Tamper
K10 Family <mark>Mixed-Signa</mark> l	K11/12 Family Baseline w/ opt. Tamper
Baseline	K02 Family L-Series Bridge

**Comprehensive Enablement - Hardware and Software Scalability** 



## Introducing ...









### **K2** – The Next Generation of Kinetis Solutions



The next generation of Kinetis solutions builds on its strong history of scalability and innovation paired with an even more expansive set of enablement solutions

- Speed application development with a comprehensive set of new tools built upon the already strong Kinetis Enablement
- A New standard of Cortex M3/M4 power efficiency with an unbeatable low dynamic power consumption from 100 to 180MHz while delivering 7x lower static power compared with the closest competitor



External Use | 14

 New Lower price points with better enablement, power/performance efficiency and smart integration. Kinetis K2 starting at \$0.79 (10ku RSL) with Cortex-M4, 100MHz, FPU and 64KB of Flash Memory



### K2 - A New High of Cortex M3/M4 power efficiency with New Lows in Prices

### Second Generation of Kinetis K devices

- A New standard of Cortex M3/M4 power efficiency
  - 125uA/MHz in VLPR mode (4MHz)
  - 160uA/MHz in Run Compute (100MHz)
  - 170uA/MHz in Run
  - 2.6uA low power mode with full state retention, wake-up time of 6uS
  - 150nA in the Lowest mode
- Full Series of Cost-Effective Devices

External Use

 Total of 65 Part Number already in production, 21 more to be launch further in 2014



### K2 – Break thought investment in Software Development

- A comprehensive set of new tools built upon the already strong Kinetis Enablement
  - Kinetis Software Development Kit (SDK)
  - Kinetis Design Studio (KDS)
  - Kinetis Bootloader
  - Addition of mbed support to the Kinetis K-Series
  - Expansion of ultra-low-cost Freedom Boards for K-Series
- New tools being launched with K2, initially based on the second generation of K-Series devices as a starting point. Will cover the full Kinetis Series with updated releases



### **Broad Scalability at New Price Points**

 Next-generation Kinetis K series devices add to the existing large Kinetis MCU portfolio, adding new combinations of memory sizes, packaging and integration, allowing customers and even broader selection of products at even lower price points.



#### **Preserve engineering investment**

 Broad and fast-growing portfolio of more than 900 Kinetis MCU solutions with software and hardware compatibility



### Lowest-priced ARM<sup>®</sup> Cortex <sup>®</sup>-M4-based device

 Next-generation devices start at 100 MHz with floating point unit, 64 KB Flash at just \$.79 (USD)



#### **Streamlined Feature Set**

 Optimized on-chip integration with BOM-saving features such as crystal-less USB device functionality









### **Kinetis K Series Portfolio**

ARM Cortex-M4 solutions for a wide range of embedded applications



### K24F – K64F – K63F - Market Trends and Applications



### Market Trends

Smarter Consumer and Industrial Devices with:

- Increased functionality
- Highly connected
- More advanced HMIs (for things like smart thermostats)
- Small form factor

### Applications

#### Consumer

- Gaming systems
- Wearables
- Smart Phone / Tablets Accessories

#### Metering

- Connected Meters
- Smart-Grid Concentrators

#### **Building & Home Automation**

- Connected Security & access control
- Smart Thermostats

Point of Sale &Secure Applications Factory Automation Portable Instrumentation



### K66/K65 180MHz Devices (2MB Flash, 256KB SRAM)

#### Key Features:

- Core/System
  - Cortex-M4 @ 180 MHz with 8KB I-Cache and FPU
- Memory
  - up to 2MB Flash,
  - up to 256KB SRAM
- Communications
  - USB OTG FS/LS w/ PHY and USB Vreg.
  - USB OTG LS/FS/HS w/PHY
  - Crystal-less USB device capability
  - Ethernet
  - Multiple serial ports including dual CAN
- Analog
  - 4 x ACMP,
  - 2x 16-bit ADC, Up to 2 x 12-bit DAC
  - Analog Vref
- Others
  - 1.71V-3.6V; -40 to 105oC
  - up to 105 x I/Os (3V)
  - Tamper and Crypto acceleration
  - 144LQFP, 144BGA, 169MBGA 169WCSP
- Availability
  - Samples: 1Q2014
  - Qual/Production: early 3Q2014





### New K22F/K02F – 64KB to 512KB -100/120MHz:

What is Available Now?! <a href="http://compass.freescale.net/go/K22F\_Alpha">http://compass.freescale.net/go/K22F\_Alpha</a>

✓ MCU samples in inventory:

Samples Partnumber	Max. Freq.	Pin Count	Package	Flash	SRAM
PK22FN512VDC12	120MHz	121	XFBGA	512K	128KB
PK22FN512VLL12	120MHz	100	LQFP	512K	128KB
PK22FN512VLH12	120MHz	64	LQFP	512K	128KB
PK22FN256VDC12	120MHz	121	XFBGA	256K	48KB
PK22FN256VMP12	120MHz	64	BGA	256K	48KB

- ✓ Tower Boards: X-TWR-K22F120M
  - with User Manual
  - Design files (schematic, BOM,...)
- ✓IDE Support:
  - IAR 7.10.1
  - Keil
- ✓ Sample Code
  - With Quick Start Guide

✓MQX support - release 4.1



- ✓ MCU offer update in the KPUR
  - including 10ku/y pricing
  - volume quotes contact Tactical Marketing or Business Development Team.

- ✓NDA Documentation
  - Customer Presentation
  - Product Brief
  - Preliminary Datasheet's
  - Preliminary Reference Manual
  - Preliminary Errata

✓ Questions: Paulo.K@freescale.com



### Conclusion



### **K2** – The Next Generation of Kinetis Solutions

- Extend Kinetis Enablement with further easy-of-use
- Introduce next level of performance, feature, and cost-effective K-Series devices



Kinetis K2 becomes the new Low-Power Reference for ARM Cortex-M3/4 "beyond 100DMIPS with FPU" for both dynamic and static modes



'K2' priced aggressively for Market Share gain having a 10-20% discount over K-Series 1st generation



Samples and TWR boards available now, announcement at FTF and production ramp-up through summer of 2014.







## General Purpose Kinetis L Product Lines





### **Kinetis L Series**

Ultra Low Power, Ultra Small Scale, Super Easy to Use, Leading Scalability and Integration as an ideal solution for Internet of Things edge nodes



#### World's Most Energy Efficient ARM based Microcontroller

Architected for power efficiency, the Kinetis L series takes advantage of ARM's ultra low power Cortex-M0+ processor and features peripherals that help you optimize power consumption. Kinetis L series provide ultra low dynamic consumption, ultra low static consumption, rich low power modes and innovative low power peripherals.



#### World's Smallest ARM based Microcontroller

Built on Freescale leading technology, Kinetis L series provide rich package options from 8x8mm2 121XFBGA, 10x10mm2 100LQFP all the way down to world's smallest KL03 20WLCSP with 1.6x2mm2 ultra small scale device.



## World's Leading Scalability and Integration with Super Ease of Use

Built on the ARM Cortex-M0+ core, the Kinetis L series simplifies development with an upward migration path to Kinetis K and X series. With a comprehensive enablement bundle including low cost Tower System and Freedom Tools, Kinetis Design Studio IDE, Kinetis Software Development Kit, MQX RTOS and the ARM support ecosystem, development is super simple. Expanding on wellknown features of the Kinetis platform with leading scalability, best-in-class integration with rich analog features and low-power connectivity, the Kinetis L series redefines entry-level.



### **Implications for Entry-Level MCUs**

8/16-bit MCUs 32-bit MCUs Connectivity 😢 Bluetooth **User Interface** Maximum Oltra-low sleep/ Power **Energy efficiency** power-down Consumption (CoreMark<sup>®</sup>/mW) currents sin log Computation n Software/Cost Unique platforms, Scalable, reusable platforms with of Ownership MCU dependent/\$\$\$ modern software techniques/\$ Limited choice, **Broad MCU portfolios, Scalability** single source multi-source



### Kinetis L Series MCUs: Enabling Differentiation in Entry-Level Products

32-bit

Energy efficiency Class-leading CoreMark/mW

## Scalability and integration

Kinetis L to K Series MCUs (ARM Cortex-M0+ to Coretex-M4)

#### Enablement

Freescale bundle + ARM ecosystem



### Kinetis L Series MCUs The evolution of the entry-level MCU

8-bit

Ultra-low static <1uA

Low cost From <\$0.50

Ease of use Freedom Platform, Processor Expert and MCU Solution Advisor







### **Kinetis L Series MCUs: Target Applications**



### **Kinetis L Series MCUs Feature Overview**

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Common Features	Optional Features														
System	Family	Flash	SRAM	Pin Count	Key Features										
Cortex-M0+ Core, 48/72 MHz					USB	SLCD	DMA	RTC	ADC	DAC	125	TSI	ROM	Vref	Security
Multi-Low-Power Modes and	KL46	128-256 KB	16-32 KB	64-121	OTG	Y	Y	Y	16-bit	12-bit	Y	Y			
Peripherals, Low-Power Boot, Clock Gating	KL43	128-256 KB	16-32 KB	48-64	Slave	Y	Y	Y	16-bit	12-bit	Y		Y	Y	
1.71-3.6 V, -40 °C to 105 °C [1]	KL36	64-256 KB	8-32 KB	64-121		Y	Y	Y	16-bit	12-bit	Y	Y			
Memory	KL34	64 KB	8 KB	64-100		Y	Y	Y	12-bit						
90 nm TFS Flash, SRAM	KL33	32-256 KB	4-32 KB	64		Y	Y	Y	16-bit	12-bit	Y		Y	Y	
Internal Memory	KL28	256-512 KB	128 KB	64-121	OTG		Y	Y	16-bit	12-bit	Y	Y	Y	Y	Y
Security/Protection	KL27	32-256 KB	8-32 KB	32-64	Slave		Y	Y	16-bit	12-bit	Y		Y	Y	
Analog Peripherals	KL26	32-256 KB	4-32 KB	32-121	OTG		Y	Y	16-bit	12-bit	Y	Y			
12/16-bit ADC, 12-bit DAC	KL25	32-128 KB	4-16 KB	32-80	OTG		Y	Y	16-bit	12-bit		Y			
High-Speed Comparator	KL24	32-64 KB	4-8 KB	32-80	OTG		Y	Y	16-bit	12-bit					
Serial Interfaces	KL17	32-256 KB	8-32 KB	32-64			Y	Y	16-bit	12-bit	Y		Y	Y	
UART (Including 1 LPUART)	KL16	32-256 KB	4-32 KB	32-64			Y	Y	16-bit	12-bit	Y	Y			
SPI, I <sup>2</sup> C	KL15	32-128 KB	4-16 KB	32-80			Y	Y	16-bit	12-bit		Y			
Timers	KL14	32-64KB	4-8 KB	32-80			Y	Y	16-bit	12-bit					
Real-Time Clock <sup>[2]</sup>	KL05	8-32 KB	1-4 KB	24-48			Y	Y	12-bit	12-bit		Y			
16-bit Low-Power TPMs (GP	KL04	8-32 KB	1-4 KB	24-48			Y	Y	12-bit						
Timer/PWM)	KL03	8-32 KB	2 KB	16-24				Y	12-bit				Y	Y	
Low-Power Timers	KL02	8-32 KB	1-4 KB	16-32					12-bit						

32-bit Periodic Interrupt Timer





### **Kinetis L Series MCUs Availability**

Pricing from <\$.49 SRP @ 10,000 units

Product Family	Flash Memory	10K # Suggested Resale Price	General Market Availability	Volume Production
KL46/36/34	64-256 KB	\$1.71 - \$2.73	Now	Now
KL43/33	64-256KB	\$1.77 - \$2.69	Q3 '14	Q3'14
KL28	256-512KB	\$2.85 - \$3.47	Q2'15	Q2'15
KL27/17	128-256KB	\$0.96 - \$2.27	Q3 '14	Q3'14
KL26/16	32-256 KB	\$0.96 - \$2.29	Now	Now
KL25/24	32-128 KB	\$1.30 - \$2.01	Now	Now
KL15/14	32-128 KB	\$0.97 - \$1.79	Now	Now
KL05/04	8-32 KB	\$0.62 - \$1.03	Now	Now
KL03	8-32KB	\$0.49 - \$0.93	Q2'14	Q2'14
KL02	8-32 KB	\$0.49 - \$0.86	Now	Now
• ••• •				





### **Kinetis KL03**

#### Packages

- 24QFN 4x4x0.65/0.5mm
- 16QFN 3x3x0.65/0.5mm
- 20WLCSP 1.6x2.0x0.56/0.4mm

#### **Features Highlight**

- ROM boot loader for easy flash upgrade
- High Speed I2C up to 1Mbps
- Embedded 1.2V voltage reference for ADC
- 35uA/MHz VLPR and 1uA sleep
- (50uA/MHz, 2uA)

#### Availability

- Sample: Mar'14
- Production: Jul'14





### **KL03 New Family Summary**



- Packages
  - 24QFN, 16QFN, 20WLCSP
- New Features
  - ROM with Boot Loader
  - 1.2V Internal Voltage Reference
  - High Speed I2C
- Availability

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- PK samples of all packages available NOW!
- X-FRDM-KL03Z available NOW!
- Market launch and production (24QFN) on 25-July!



### Kinetis KL43/33

#### Packages

- 64LQFP 10x10x1/0.5mm
- 64MAPBGA 5x5x1/0.5mm

#### **Features Highlight**

- ROM boot loader for easy flash upgrade
- Crystal-less USB Slave
- High Speed IIC up to 1Mbps
- Embedded 1.2V voltage reference for ADC
- FlexIO module
- 60uA/MHz VLPR and 1.5uA sleep

#### Availability

- Sample: NOW
- Production: July'14





### KL43/33 New Family Summary



- Packages
  - 64LQFP, 64MAPBGA
- New Features
  - ROM with Boot Loader
  - 1.2V Internal Voltage Reference
  - High Speed I2C
  - Crystal-less USB
  - FlexIO
- Availability
  - PK samples (64LQFP) available NOW!
  - X-FRDM-KL43Z and X-TWR-KL43Z48M available on 25-May!
  - Market launch and production (64LQFP) on 1-July!



### Kinetis KL27/17

#### Packages

- 64LQFP 10x10x1/0.5mm
- 64MAPBGA 5x5x1/0.5mm
- 48QFN 7x7x0.65/0.5mm
- 32QFN 5x5x0.65/0.5mm

#### **Features Highlight**

- ROM boot loader for easy flash upgrade
- Crystal-less USB Slave
- High Speed IIC up to 1Mbps
- Embedded 1.2V voltage reference for ADC
- FlexIO module
- 60uA/MHz VLPR and 1.5uA sleep

#### Availability

- Sample: NOW
- Production: July'14





### **KL27/17 New Family Summary**



- Packages
  - 64LQFP, 64MAPBGA, 48QFN, 32QFN
- New Features
  - ROM with Boot Loader
  - 1.2V Internal Voltage Reference
  - High Speed I2C
  - Crystal-less USB
  - FlexIO
- Availability
  - PK samples (64LQFP) available NOW!
  - X-FRDM-KL43Z and X-TWR-KL43Z48M available on 25-May!
  - Market launch and production (64LQFP) on 1-July!



### Kinetis KL27/17

#### Packages

- 64LQFP 10x10x1/0.5mm
- 36XFBGA
   3.5x3.5x0.5/0.5mm
- 64MAPBGA 5x5x0.5/0.5mm
- 36WLCSP 2.3x2.3x0.5/0.35mm
- 48QFN 7x7x0.65/0.5mm
- 32QFN 5x5x0.65/0.5mm

#### **Features Highlight**

- ROM boot loader for easy flash upgrade
- Crystal-less USB Slave
- High-speed I2C up to 1Mbps
- FlexIO module
- CRC for data correction
- 40uA/MHz in VLPR and 1uA in sleep (with RTC and RAM retention)
- USB connection keep alive in sleep mode

#### Availability

- Sample: 30-Aug'14 (64LQFP), 18-Sept'14 (36XFBGA)
- Production: 31-Oct'14 (64LQFP), 30-Dec'14 (36XFBGA)





### Kinetis KL28/28S

#### Packages

- 121XFBGA 8x8x1/0.65mm
- 100LQFP 14x14x1/0.5mm
- 64MAPBGA 5x5x0.65/0.5mm
- 64LQFP 10x10x1/0.5mm
- WLCSP TBD

#### **Features Highlight**

- 72MHz core speed with large memory size
- ROM boot loader for easy flash upgrade
- Black Box
- Crystal-less USB Slave
- High-speed I2C up to 1Mbps
- Embedded 1.2V voltage reference for ADC
- FlexIO module
- 75uA/MHz run and 4uA sleep

#### Availability

- Sample: Q4'14
- Production: Q2'15







L Series Technical Differentiators



### **Kinetis L Series MCUs: Energy Efficiency**

Ultra-efficient processing	<ul> <li>Cortex-M0+ processor</li> <li>90 nm low-power flash technology</li> <li>Bit manipulation engine</li> <li>&lt;40 uA/MHz, 4.8 CM/mW</li> <li>Peripheral bridge crossbar</li> <li>Zero wait state Flash memory controller</li> </ul>	INSIGHT
Ultra-low- power modes	<ul> <li>90nm low-leakage flash technology</li> <li>Multiple run, wait and stop modes</li> <li>4 us wake-up from deep sleep modes</li> <li>Clock &amp; power gating, low-power boot options</li> <li>2 uA deep sleep Idd with register retention, LVD active and 4.3 us wake-up</li> </ul>	AWARDS Most Innovative Process Technology Kinetis ARM
Energy-saving peripherals	<ul> <li>Smart peripherals function in deep sleep modes and can make intelligent decisions and process data without waking up the core—ADMA, UART, timers, ADC, segment LCD, touch sensing</li> </ul>	Cortex-M4 MCUs



#### Inter-module-connection with aDMA

Peripheral	Wakeup source	<ul> <li>Kinetis L-Series devices support DMA operation in low power modes</li> </ul>								
Touch Sense Interface	End of scan Scan out of range	<ul> <li>Stop modes can be entered with the System Clock enabled</li> </ul>								
CMP	Compare detected	<ul> <li>Allows peripherals with STOP mode functionality to trigger asynchronous DMA request</li> </ul>								
I2S	Receive data ready Transmit data needed	<ul> <li>The MCU will wake from STOP mode to WAIT, process the DMA request and</li> </ul>								
LPUART	Receive data ready Transmit data needed	then re-enter the STOP mode with no CPU intervention								
LPTPM	Compare/capture detected Counter overflow	<ul> <li>The MCU can be placed in a Compute mode with peripherals configured for STOP.</li> </ul>								
Port Control and Interrupts	External edge detected	In this mode, the CPU can continue to process data at very low dynamic power Peripherals with STOP mode								
ADC	Conversion complete	functionality can continue to operate and trigger DMA transfers								
	Use Case: ADC performing conversions DMA transferring									

**Use Case:** ADC performing conversions, DMA transferring conversion results into RAM buffer and CPU processing/filtering the data all done with minimal power ~ 300uA at 4MHz Core speed



### **Power Consumed in a "Typical" Application**

Use Case Wolverine Whitepaper

"Given that ultra-low-power devices spend 99.9 percent of the time in standby mode, leakage current has become a key factor in determining power efficiency in smaller process geometries."



eescale

**Average Current Consumption** 



#### **Use Case Details:**

- 99.9% of time in standby with RTC active
  - Kinetis L—VLLS1+RTC
  - Wolverine—LPM3 + RTC

#### **Conclusions:**

- Running at same frequency, Kinetis L consumes 15–20% less average current.
- However, Kinetis L delivers nearly 2x the work or can do the same work at roughly half the frequency.
- In this case, Kinetis delivers on the "typical use case" at nearly 40% less average current.





### **Kinetis L Series MCUs: Entry-Level Enablement**

#### Hardware

#### Freescale Freedom Development Platform

FRDM-KL02Z FRDM-KL05Z FRDM-KL25Z FRDM-KL26Z FRDM-KL46Z

- Low-cost/power platform for entry-level developers (\$12.95/€10 SRP)
- Integrates a fully featured debugger that works with all featured tool chains



#### Freescale Tower System

#### TWR-KL46Z48M TWR-KL25Z48M

 Modular, open source development platform with reusable peripheral modules offering connectivity, analog, graphics LCD and motor control functionality



#### **IDE & Code Generation**

#### Freescale & Third-Party IDEs

- Freescale CodeWarrior v10.3: free 64KB
- Keil MDK: free 32 KB
- IAR EWARM: free 32 KB
- Atollic TrueStudio: free 8 KB
- GCC ARM Embedded via Launchpad.net
- Additional tool support from Code Red and others in Q412

#### Freescale *Processor Expert* Code Generator

- Free software generation tool for device drivers/start-up code
- Seven steps from project creation to debug dramatically reduces development time
- Available within CodeWarrior or as a standalone plug-in for IAR/Keil/GNU IDEs



#### Run-Time Software & Product Selector

#### Freescale MQX Lite RTOS

#### www.freescale.com/mqx

- Free, lightweight MQX kernel customised for small resource MCUs
- Packaged as a Processor Expert component
- Upwards compatible with MQX RTOS



### Solution Advisor

- · Web-based interactive MCU selector
- Filters for operating characteristics, packaging, memory configuration and peripherals. Verifies muxing compatibility.
- Save, download and print summary reports and pin muxing configurations.













### **Kinetis Solution Overview**

#### Kinetis MCU

ARM Cortex-M0+ Core 48MHz, 1.77 CoreMark/MHz, 2-Stage Pipeline, 1-Cycle GPIO, Micro Trace Buffer

ARM Cortex-M4 Core 50-150MHz, 3.40 CoreMark/MHz, HW-divide, MAC, DSPcommands, FPU option

#### Differentiators

Low-power, Performance, Flex-Memory, Mixed-Signal, Security, HMI Features

#### **Special Functions**

Analog Pre-Processing, 24b-Sigma Delta ADC, sub -1GHz & 2.4 GHz Transceiver



### The Growing Importance of Software





"reescale"

### **Freescale's Microcontroller Enablement Bundle**





#### Robust Software & Development Ecosystem Applications



Learn more at: www.freescale.com/KQ

### Kinetis Software Development Kit (SDK)





A complete software framework for developing applications across all Kinetis MCUs



HAL, peripheral drivers, libraries, middleware, utilities, and usage examples.



#### **Product Features**

- Open source Hardware Abstraction Layer (HAL) provides APIs for all Kinetis hardware resources
- BSD-licensed set of peripheral drivers with easy-touse C-language APIs
- Comprehensive HAL and driver usage examples and sample applications for RTOS and bare-metal.
- CMSIS-CORE compatible startup and drivers plus CMSIS-DSP library and examples
- RTOS Abstraction Layer (OSA) with support for Freescale MQX, FreeRTOS, Micrium uC/OS, baremetal and more
- Integrates USB and TCP/IP stacks, touch sensing software, encryption and math/DSP libraries, and more
- Support for multiple toolchains including GNU GCC, IAR, Keil, and Kinetis Design Studio



### **Kinetis Design Studio**



No-cost integrated development environment (IDE) for Kinetis MCUs



Eclipse and GCCbased IDE for C/C++ editing, compiling and debugging



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#### **Product Features**

- A free of charge and unlimited IDE for Kinetis MCUs
- A basic IDE that offers robust editing, compiling and debugging
- Based on Eclipse, GCC, GDB and other open-source technologies
- Includes Processor Expert with Kinetis Platform SDK integration
- Host operating systems:
  - Windows 7/8
  - Linux (Ubuntu, Redhat, Centos)
  - Mac OS X
- Support for SEGGER, P&E and Open SDA/CMSIS-DAP debugger targets
- Support for Eclipse plug-ins including RTOSawareness (i.e. MQX, FreeRTOS)
- CodeWarrior project importer



### **Kinetis Bootloader**





In-system flash programming over a serial connection: erase, program, verify



ROM or flash based bootloader with opensource software and host-side programming utilities.



### **Product Features**



- A common bootloader for all Kinetis MCUs
- Source code provided under a permissive BSD open source license
- ROM based on select Kinetis devices
- Pre-programmed into flash (on devices without a dedicated ROM) for built-in factory programming capabilities
- Fully customizable for use in customer applications providing reliable field updates
- Serial communications with a host via UART, SPI, I2C, USB HID, or CAN
  - Active peripheral detection
  - Common command protocol for all peripherals.
- Command-line and GUI tools provided for Windows, Linux and Mac hosts



### Kinetis K2 Tools Solutions (Addition to existing Kinetis Enablement)

#### ✓ mbed Support – Expanding to Kinetis K-Series **Families**



Rapid and easy Kinetis prototyping and development through the global mbed Developer Community providing free software libraries

#### ✓ Expand Offer of K-Series Freedom Boards



Ultra low-cost/low-power development platform

Enables guick application prototyping and demonstration of Kinetis MCU families

FRDM-K64F: Freescale Freedom Development Platform



#### Software

C/C++ Programs							
mbed Components Database Accelerometer, GPS, 802.15.4/6LoWPAN, Cellular, Compass,							
mbed SDK Runtime, Memory Model, Peripheral APIs, STDIO, RTOS, Networking, Platform features							
Low Level Driver Libraries	Toolchain C library	RTOS					
CMSIS-CORE							









Freescale Kinetis L combined with WLCSP packing brings the next World's Smallest ARM® Powered MCU Microscopic Package. Massive Potential.

- 1.6 mm x 2.0 mm x 0.56 mm
- Advanced wafer-level chip scale package for the ultimate in PCB area reduction
- 35% less PCB area, yet delivers 60% more GPIO than the next competing solution
- 32-bit ARM® Cortex<sup>™</sup>-M0+ core with high density feature integration: 32 KB flash, precision analog, ultra low power and more
- Start developing with the Kinetis L series
   Freescale Freedom development platform
- Sampling in April 2014!





For more information, visit freescale.com/Kinetis/KL03CSP





# Freescale CSP Packaging Overview for 32-bit Kinetis MCUs

- What is Wafer Level CSP?
  - Wafer Level Chip Scale Package refers to the technology of packaging an integrated circuit at the wafer level, instead of the traditional process of assembling individual units in packages after dicing them from a wafer.
- What will it mean for me as a customer buying and mounting CSP package into my system
  - The cost will be higher. Handling is more complex and thus cost of both handling and soldering process more expensive
  - More information on Freescale recommended handling is available in an Application Note see AN3846
- CSPs are not targeted at low volume customers. For 2014, only High Touch accounts backed by Business Development Marketing will be supported.



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### **Alternative to CSPs**

- With the higher cost of CSP and difficult handling, customers should consider some alternative options before selecting a CSP.
- If the customer requirement is only for a very thin package, and area is not a major concern, customers should consider the new 121 pin Ultra Fine BGA packages being supported on new products.
  - The use of the ultra fine BGA will lead to a lower cost PCB than that which utilizes a CSP.
- Other alternatives to CSP:
  - 24, 32 or 48 QFN
  - -64, 121 & 144MAPBGA

External Use



### **Kinetis WLCSP Portfolio**

The World's Smallest ARM Powered MCUs – From ultra low power to high performance



### **CSP** options on Kinetis – Qualified

Device	Part #	Flash	Speed Grade	Temp range	Package	Dimensions (mm)	Comment
KL02	MKL02Z32CAF4R KKL02Z32CAF4R	32KB	48MHz		20WLCSP	1.994 x 1.94 x 0.563*	
KL15	MKL15Z128CAD4R KKL15Z128CAD4R	15Z128CAD4R 128kB 48MHz 15Z128CAD4R 128kB 48MHz			35WLCSP	2.37 x 2.46*	18wk lead-time for Production
KL16	MKL16Z128CAL4 KKL16Z128CAL4	128kB	48MHz	Max Ambient = - 40 to 85oC	36WLCSP	2.5 x3 x 0.528**	0.35mm ball pitch
KL26	MKL26Z128CAL4 KKL26Z128CAL4	128kB	48MHz		36WLCSP	2.5 x3 x 0.528**	0.35mm ball pitch
K60 K20	MK60DN512ZCAB10R KK60DN512ZCAB10R MK20DN512ZCAB10R KK20DN512ZCAB10R	512KB	100MHz		120WLCSP	5.29 x 5.28 x 0.563*	
K60	SCK60FN1MGCAA12R	1MB	120MHz		143WLCSP	6.44 x 5.55x 0.563*	
K61	MK61FN1M0CAA12R KK61FN1M0CAA12R	1MB	120MHz		143WLCSP	6.44 x 5.55x 0.563*	
K10	MK10DN512ZAB10R	512KB	100MHz	Max Ambient = 0 to 70oC	120WLCSP	5.29 x 5.28 x 0.563*	





### **CSP** options on Kinetis – Pipeline

Device	Part #	Flash	RAM	Speed	Number of balls (pitch)	Temp range	Size (mm)	PK Samples *	Qual *	Production *
K24 / K64	MK24FN1M0CAJ12R MK64FN1M0CAJ12R	1MB	256Kb	120MHz	142 (0.4mm)		4.8 x 5.6 x 0.563*	Now	TBD by Customer demand	18wk lead- time
K65	MK65FN2M0CAC18R MK65FX1M0CAC18R	2MB	256Kb	180MHz	169 (0.4mm)		5.6 x 5.5 x 0.563*	Now	May'14	July '14
KL03	MKL03Z32xxx4	32kB	4Kb	48MHz	20 (0.4mm)	Moy	2.0 x 1.6 x 0.563*	April '14	June'14	July'14
K22F	MK22FN256CAH12 MK22FN128CAH12	256kb or 128kB	48Kb	120MHz	64 (0.4mm)	Ambient = -40 to 85oC	3.4 x 3.2 x 0.563*	Now	TBD by Customer demand	18wk lead- time
K22F	MK22FN512CAP12 MK22FN256CAP12	512kb or 256kB	128Kb	120MHz	80 (0.4mm)		4.12 x 3.56 x 0.563*	TBD	TBD	TBD
K22F	K22FN128CAK10	128kB	24Kb	100MHz	49 (0.4mm)		TBD x 0.563*	TBD	TBD	TBD
K02	K02FN128Cxx10 K02FN64Cxx10	12kB or 64kB	16Kb	100MHz	TBD		TBD	TBD	TBD	TBD



\* Dates subject to change



### **Typical WLCSP Milestones - TBC**

#### Mechanical samples: 4 - 6 weeks after silicon validation (confidence)

- Mechanical Samples WLCSP samples are not tested. Part configurations and IP trims not programmed. Parts can be used to validate the RDL (re-distribution layer) and the case outline.
- Pre-bump probe only, limited test samples: + 6 weeks after CSP mask design
- Ball map must be agreed by customer and RDL feasibility is complete
  - Probe-only (Limited Test) Samples WLCSP sample are tested with appropriate part configurations, IP trims, and NVM initialized. However, parts are not tested or validated after bump processing. These can be shipped to customers for development purposes, but there is risk without validating the functionality of the parts after bump processing prior to shipment.

#### • Full test samples (@room temp): + 5 weeks (Post Bump)

 Room-Temp Samples – WLCSP sample are tested with appropriate part configurations, IP trims, and NVM initialized. Parts are 100% tested after bump processing. These can be shipped to customers for development purposes, with low risk of failure for yield issues.

#### Qualification: + 6 weeks

- Qualification generally, die itself is already qualified in standard package, additional testing and stressing to confirm WLCSP package qualification.
- Production ramp: + 12 weeks after official design WIN (+6 weeks after qual)
  - Production ramp high volume customer orders can be filled (pending appropriate lead times). Range in schedule dependent on production hardware availability or creation.



### Wafer Level Chip Scale Packaging

- Packaging of microcontroller assembled at the wafer level
- The package is of the same size as the die
- Interconnections from the die to the PCB are accomplished by solder balls
- No bond wires or interposer connections are required

### **Key Advantages:**

- It allows the miniaturization of embedded applications
- The die to PCB inductance is minimized

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Enhanced thermal conduction characteristic

PCB Layout Application Note: AN3846, Wafer Level Chip Scale Package









## - Kinetis L-series, KL02 20pin CSP

- 25% less area, 60% more GPIO than next nearest competitor
- Ultra low power Cortex-M0+
- World's smallest 128KB Flash MCU (2.4x2.5mm<sup>2</sup>)
  - Kinetis L-series, KL16 36pin CSP
  - Ultra low power Cortex-M0+
- 512KB Flash, 128KB RAM, USB, ENET (5.3x5.3mm<sup>2</sup>)
  - Kinetis K-series, K60 120pin CSP
  - High performance Cortex-M4
- 1MB Flash, 128KB RAM, USB, ENET (6.5x5.6mm<sup>2</sup>)
  - Kinetis K-series, K61 143pin CSP

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- High performance Cortex-M4



The World's Smallest ARM Powered MCUs – From ultra low power to high performance

World's smallest ARM powered MCU (1.9x2.0mm<sup>2</sup>)







### **Freescale Product Longevity Program**

- The embedded market needs long-term product support
- Freescale has a longstanding track record of providing longterm production support for our products
- Freescale is pleased to introduce a formal product longevity program for the market segments we serve
  - For the automotive and medical segments, Freescale will make a broad range of program devices available for a minimum of 15 years
  - For all other market segments in which Freescale participates, Freescale will make a broad range of devices available for a minimum of 10 years
  - Life cycles begin at the time of launch
- For terms and conditions and to see a list of participating Freescale products available under this program: <u>www.freescale.com/productlongevity</u>



## Designing with Freescale

# Tailored live, hands-on training in a city near you

### 2014 seminar topics include

- QorIQ product family update
- Kinetis K, L, E, V series MCU product training

## freescale.com/DwF







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